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In the Claims:

Please rewrite Claim 34. The requested amendments to Claim 34 are shown below on pages 3~10 of this paper in a marked-up version of that claim, as required by 37 CFR §1.121(c). Deletions are shown by strike-through, and additions are shown by underlining. A complete listing of all claims indicating the status thereof is also shown on pages 3~10.

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Listing of Claims

[including (i) amendments to Claim 34, and (ii) status of all claims (Claims 25~44 remain active)]

1~24. (canceled).

25. (previously presented) In an electronic device that comprises a substrate having conductive properties, a process for fabricating a protective layer, comprising

(a) applying to the substrate a protective layer composition to form a protective layer thereon, wherein the protective layer composition comprises a polymer comprising, as polymerized units, monomers of which at least 50 mole percent comprise a structure selected from the group consisting of:

(I)

$$\begin{array}{c|c}
O & R_1 \\
\hline
O & CH_2
\end{array}$$

wherein R₁ is hydrogen or lower alkyl, R₂ is lower alkyl, and R₃ is hydrogen or lower alkyl; wherein lower alkyl includes alkyl groups having 1 to 6 linear or cyclic carbon atoms;

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(II)

wherein R_1 is hydrogen or lower alkyl, R_2 is lower alkyl, and R_3 and R_4 are independently hydrogen or lower alkyl; wherein lower alkyl includes alkyl groups having 1 to 6 carbon atoms, and the joining of R_1 and R_2 , or R_1 and either R_3 or R_4 , or R_2 and either R_3 or R_4 , or R_2 and either R_3 or R_4 , or R_4 , or R_5 and either R_6 or R_4 , or R_6 and either R_8 or R_8 to form a 5-, 6-, or 7-membered ring;

(III)

$$---- \begin{pmatrix} CH_2 \end{pmatrix}_n C_6H_4 - O \begin{pmatrix} CH_2 \end{pmatrix}_n C_6H$$

wherein R_1 is hydrogen or lower alkyl, R_2 is lower alkyl, and R and R_4 are independently hydrogen or lower alkyl; wherein lower alkyl includes alkyl groups having 1 to 6 carbon atoms, and the joining of R_1 and R_2 , or R_1 and either R_3 or R_4 , or R_2 and either R_3 or R_4 to form a 5-, 6-, or 7-membered ring; and n is 0 to 4; and (IV) mixtures of (I), (II) and/or (III);

- (b) irradiating the protective layer through a mask;
- (c) heating the device;

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- (d) contacting the protective layer with a developing solution to remove the portions of the protective layer composition exposed to radiation in step (b) and form a patterned protective layer;
 - (e) irradiating the patterned protective layer; and
 - (f) heating the device.
- 26. (previously presented) The process of Claim 25 wherein the protective layer composition comprises a polymer comprising, as polymerized units, monomers of which at least 60 mole percent comprise a structure selected from the group consisting of (I), (II), (III) and (IV).
- 27. (previously presented) The process of Claim 25 wherein the protective layer composition comprises a polymer comprising, as polymerized units, a monomer selected from the group consisting of 1-ethoxyethyl methacrylate (or acrylate), 1-butoxyethyl methacrylate (or acrylate), 1-ethoxy-1-propyl methacrylate (or acrylate), tetrahydropyranyl methacrylate (or acrylate), tetrahydropyranyl p-vinylbenzoate, 1-ethoxy-1-propyl p-vinylbenzoate, 4-(2-tetrahydropyranyloxy)benzyl methacrylate (or acrylate), 4-(1-butoxyethoxy)benzyl methacrylate (or acrylate); and mixtures thereof.
- 28. (previously presented) The process of Claim 25 wherein the protective layer composition comprises a polymer comprising, as a polymerized unit, a monomer selected from the group consisting of t-butyl methacrylate (or acrylate); neopentyl methacrylate (or acrylate); 1-bicyclo{2,2,2}octyl methacrylate (or acrylate) and their derivatives; 1-bicyclo{2,2,1}heptyl methacrylate (or acrylate) and their derivatives; 1-bicyclo{2,1,1}hexyl methacrylate (or acrylate) and their derivatives; 1-bicyclo{1,1,1}pentyl methacrylate (or acrylate) and their derivatives; 1-

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adamantyl methacrylate (or acrylate) and their derivatives; and mixtures thereof.

- 29. (previously presented) The process of Claim 25 wherein the protective layer composition comprises a polymer comprising, as a polymerized unit, up to about 10 mole percent of a monomer selected from methyl methacrylate, methyl acrylate, methacrylic acid, and hydroxyl ethyl methacrylate; and mixtures thereof.
- 30. (previously presented) The process of Claim 25 wherein the protective layer composition comprises 0.5-30 mole% of photoacid generator and 10-1000 ppm of photosensitizer.
- 31. (previously presented) The process of Claim 25 wherein the protective layer composition has a molecular weight in the range of about 7,000 to about 1,000,000.
- 32. (previously presented) The process of Claim 25 wherein the protective layer composition comprises a copolymer.
- 33. (previously presented) The process of Claim 25 wherein the protective layer composition comprises a polymer comprising, as a polymerized unit, a monomer having a hydrophilic group.
- 34. (currently amended) A process for fabricating an electronic device that comprises a substrate having conductive properties, comprising
- (a) applying to a first side of the substrate a protective layer composition to form a protective layer thereon, wherein the protective layer composition comprises a polymer comprising, as polymerized units,

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monomers of which at least 50 mole percent comprise a structure selected from the group consisting of:

(I)

$$CH_2$$
 CH_2
 R_3

wherein R₁ is hydrogen or lower alkyl, R₂ is lower alkyl, and R₃ is hydrogen or lower alkyl; wherein lower alkyl includes alkyl groups having 1 to 6 linear or cyclic carbon atoms;

(II)

$$\begin{array}{c|cccc}
O & R_1 & H \\
\hline
O & & R_3 \\
\hline
OR_2 & R_4
\end{array}$$

wherein R_1 is hydrogen or lower alkyl, R_2 is lower alkyl, and R_3 and R_4 are independently hydrogen or lower alkyl; wherein lower alkyl includes alkyl groups having 1 to 6 carbon atoms, and the joining of R_1 and R_2 , or R_1 and either R_3 or R_4 , or R_2 and either R_3 or R_4 to form a 5-, 6-, or 7-membered ring;

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(III)

wherein R_1 is hydrogen or lower alkyl, R_2 is lower alkyl, and R and R_4 are independently hydrogen or lower alkyl; wherein lower alkyl includes alkyl groups having 1 to 6 carbon atoms, and the joining of R_1 and R_2 , or R_1 and either R_3 or R_4 , or R_2 and either R_3 or R_4 to form a 5-, 6-, or 7-membered ring; and n is 0 to 4; and (IV) mixtures of (I), (II) and/or (III);

- (b) irradiating the protective layer through a mask;
- (c) heating the device;
- (d) contacting the protective layer with a developing solution to remove the portions of the protective layer composition exposed to radiation in step (b) and form a patterned protective layer;
 - (e) irradiating the patterned protective layer;
 - (f) heating the device;
- (g) applying to the patterned protective layer a paste composition;
- (h) irradiating the device from the backside a second side of the substrate to form a pattern in the paste composition; and
- (i) contacting the paste composition and the patterned protective layer with a developing solution to remove (I) the portions of the paste composition not exposed to radiation in step (h), and (II) the patterned protective layer.

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- 35. (previously presented) The process of Claim 34 wherein the protective layer composition comprises a polymer comprising, as polymerized units, monomers of which at least 60 mole percent comprise a structure selected from the group consisting of (I), (II), (III) and (IV).
- 36. (previously presented) The process of Claim 34 wherein the protective layer composition comprises a polymer comprising, as polymerized units, a monomer selected from the group consisting of 1-ethoxyethyl methacrylate (or acrylate), 1-butoxyethyl methacrylate (or acrylate), 1-ethoxy-1-propyl methacrylate (or acrylate), tetrahydropyranyl methacrylate (or acrylate), tetrahydropyranyl p-vinylbenzoate, 1-ethoxy-1-propyl p-vinylbenzoate, 4-(2-tetrahydropyranyloxy)benzyl methacrylate (or acrylate), 4-(1-butoxyethoxy)benzyl methacrylate (or acrylate); and mixtures thereof.
- 37. (previously presented) The process of Claim 34 wherein the protective layer composition comprises a polymer comprising, as a polymerized unit, a monomer selected from the group consisting of t-butyl methacrylate (or acrylate); neopentyl methacrylate (or acrylate); 1-bicyclo{2,2,2}octyl methacrylate (or acrylate) and their derivatives; 1-bicyclo{2,2,1}heptyl methacrylate (or acrylate) and their derivatives; 1-bicyclo{2,1,1}hexyl methacrylate (or acrylate) and their derivatives; 1-bicyclo{1,1,1}pentyl methacrylate (or acrylate) and their derivatives; 1-adamantyl methacrylate (or acrylate) and their derivatives; and mixtures thereof.
- 38. (previously presented) The process of Claim 34 wherein the protective layer composition comprises a polymer comprising, as a polymerized unit, up to about 10 mole percent of a monomer selected from,

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methyl methacrylate, methyl acrylate, methacrylic acid, and hydroxyl ethyl methacrylate; and mixtures thereof.

- 39. (previously presented) The process of Claim 34 wherein the protective layer composition comprises 0.5-30 mole% of photoacid generator and 10-1000 ppm of photosensitizer.
- 40. (previously presented) The process of Claim 34 wherein the protective layer composition has a molecular weight in the range of about 7,000 to about 1,000,000.
- 41. (previously presented) The process of Claim 34 wherein the protective layer composition comprises a copolymer.
- 42. (previously presented) The process of Claim 34 wherein the protective layer composition comprises a polymer comprising, as a polymerized unit, a monomer having a hydrophilic group.
- 43. (previously presented) The process of Claim 34 wherein the paste composition comprises silver.
- 44. (previously presented) The process of Claim 34 wherein the paste composition comprises carbon nanotubes.